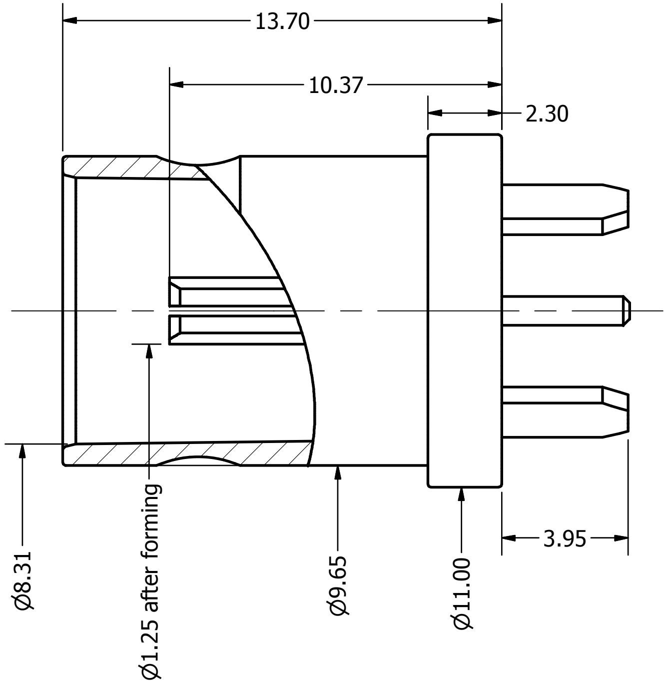

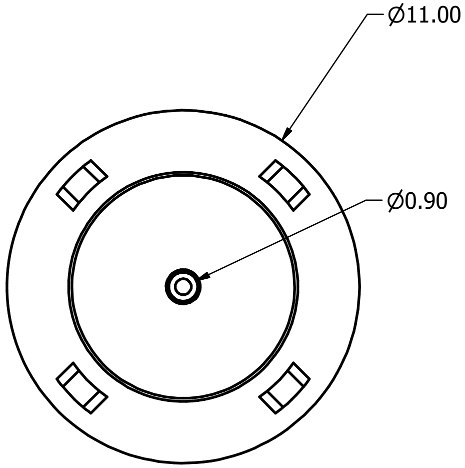

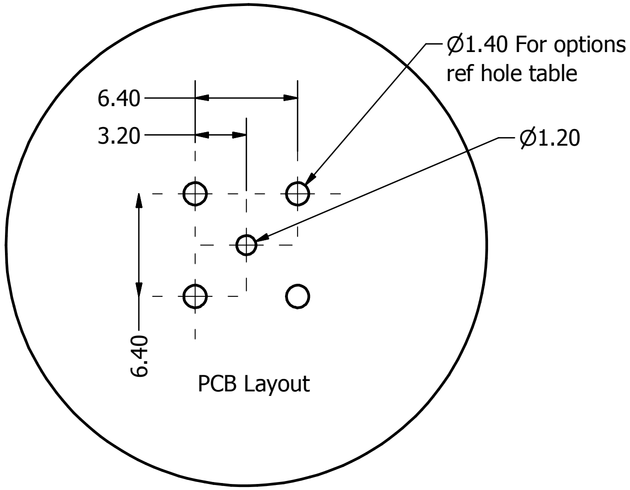

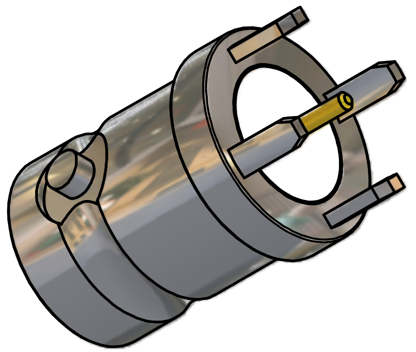

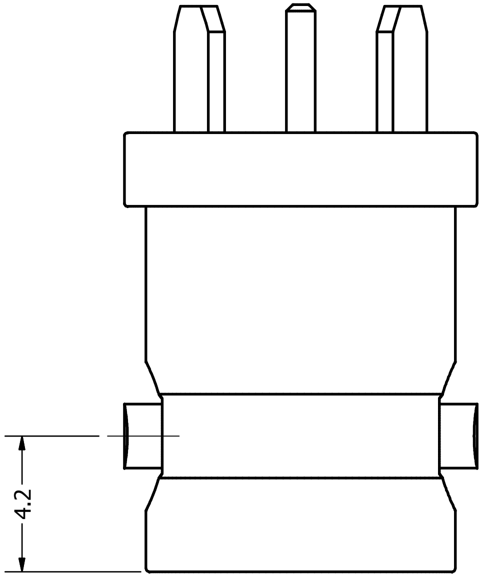

Comments	Hole Dia (mm)	Plating Thickness		Pad Dia (mm)
		Cu	Sn/Pb	
	1.3	0.03-0.08	0.008	2.0
Recommended for PCB thicknesses >1.6mm	1.4	0.03-0.08	0.008	2.2
	1.5	0.03-0.08	0.008	2.3
Centre Pin	1.2	0.03-0.08	0.008	1.8

REVISION HISTORY

REV	DESCRIPTION	DATE	APPROVED
1.1	Part No Issued	26/10/2006	Peter Fayers
1.2	Additional Dims	26/11/2008	P. Fayers

Status: Pending	Material: Brass/PhosBronz/PTFE	Finish: Ni/Au/Nat	Gen Tol +/- 0.20	DO NOT SCALE
	Designed by Peter Fayers / Checked by	Approved by / Date	©2006	Date 26/10/2006 / A3
	C.E.I. Ltd / RoHS COMPLIANT		BNC (F) Pressfit Hybrid 75 Ohm	
			C-SX-061 Cust Drawing	Issue 1.2 / Sheet 1 / 1